

IN THE CLAIMS

B2 2. (Amended) The structure as recited in claim 1, wherein the metal layer includes copper.

B3 4. (Amended) The structure as recited in claim 1, further comprising a barrier layer disposed between the interconnect and the metal layer to prevent diffusion therebetween.

B4 11. (Amended) The structure as recited in claim 10, wherein the metal layer includes copper.